

**What is claimed:**

1. An electronic package comprising:

a metal member;

a dielectric layer positioned on said metal member;

an active element positioned on said dielectric layer;

a first plurality of electrically conductive members positioned on said dielectric layer relative to said active element;

a plurality of metallic traces on said dielectric layer, selected ones of said metallic traces in electrical contact with said active element and selected ones of said first plurality of electrically conductive members;

a second plurality of electrically conductive members positioned on said dielectric layer; and

at least one electrically conductive via in said dielectric layer, said at least one of said second plurality of electrically conductive members in contact with said metal member not electrically coupled to said metallic traces.

1 2. The electronic package of claim 1, wherein said  
2 dielectric layer comprises a permanent photo-imageable  
3 dielectric material.

1 3. The electronic package of claim 1, wherein said  
2 dielectric layer has a thickness of from 25 microns  
3 to 115 microns.

1 4. The electronic package of claim 1, wherein each of  
2 said plurality of metallic traces has a width of from  
3 50 microns to 260 microns.

1 5. The electronic package of claim 1, wherein said  
2 second plurality of electrically conductive members  
3 is positioned on said dielectric layer peripherally to  
4 said first plurality of electrically conductive  
5 members.

6 6. The electronic package of claim 1, further including  
7 a mother board positioned on said first and said  
8 second plurality of electrically conductive members,  
9 said mother board including a ground plane.

1 7. The electronic package of claim 6, wherein said  
2 ground plane is electrically coupled to said metal  
3 member.

1 8. The electronic package of claim 7, wherein said  
2 metal member comprises an electromagnetic shield  
3 for said active element.

1 9. A method of making an electronic package comprising:  
2 providing a metal member;  
3 positioning a dielectric layer on said metal member;  
4 positioning a first plurality of electrically  
5 conductive members on said dielectric layer;  
6 positioning an active element on said dielectric layer  
7 relative to said first plurality of electrically  
8 conductive members;  
9 positioning a plurality of metallic traces on said  
10 dielectric layer;  
11 connecting selected ones of said metallic traces with  
12 said active element and selected ones of said first  
13 plurality of electrically conductive members;  
14 positioning a second plurality of electrically  
15 conductive members on said dielectric layer;  
16 forming at least one electrically conductive via in  
17 said dielectric layer; and

18 connecting electrically said at least one of said  
19 second plurality of electrically conductive members  
20 with said metal member, said second plurality of  
21 electrically conductive members not in electrical  
22 contact with said metallic traces.

1 10. The method of claim 9, wherein forming said at least  
2 one electrically conductive via is achieved using  
3 photolithography processing.

1 11. The method of claim 9, wherein forming said at least  
2 one electrically conductive via is achieved using  
3 laser drilling.

Add  
A3 >